SOD323

plastic, surface-mounted package; 2 terminals; 1.7 mm x 1.25 mm x 0.95 mm body

9 January 2017 — Package information

1. Package summary

Dimensions (mm)	1.7 x 1.25 x 0.95
Terminal position code	D (double)
Package type descriptive code	SOD323
Package outline version code	SOD323
Manufacturer package code	SOD323
Package type industry code	SOD323
Package outline version description	plastic, surface-mounted package; 2 terminals; 1.7 mm x 1.25 mm x 0.95 mm body
Package style descriptive code	SOD (small outline diode)
Package body material type	P
JEITA package outline code	SC-76
Handling precautions	IC26_CHAPTER_3_2000
Thermal design considerations	SC18_1999_CHAPTER_5_2
Mounting method type	S (surface mount)
Generic mounting and soldering information	AN10365_3
Reflow soldering footprint	SOD323_fr
Wave soldering footprint	SOD323_fw
Package life cycle status	REL
Major version date	18-9-2008
Minor version date	6-7-2012
Security status	COMPANY PUBLIC
Modified date	28-11-2012
Issue date	16-3-2006
Web publication date	28-11-2012
Initial web publication date	18-1-2011
Customer specific indicator	N
Maturity	Product
Package author	Nair Deepa
Package approver	Nair Deepa

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
A	seated height		0.8	-	0.95	1.1	mm
D	package length		1.6	-	1.7	1.8	mm

Symbol	Parameter		Min	Typ	Nom	Max	Unit
E	package width		1.15	-	1.25	1.35	mm
n_2	actual quantity of termination		-	-	2	-	

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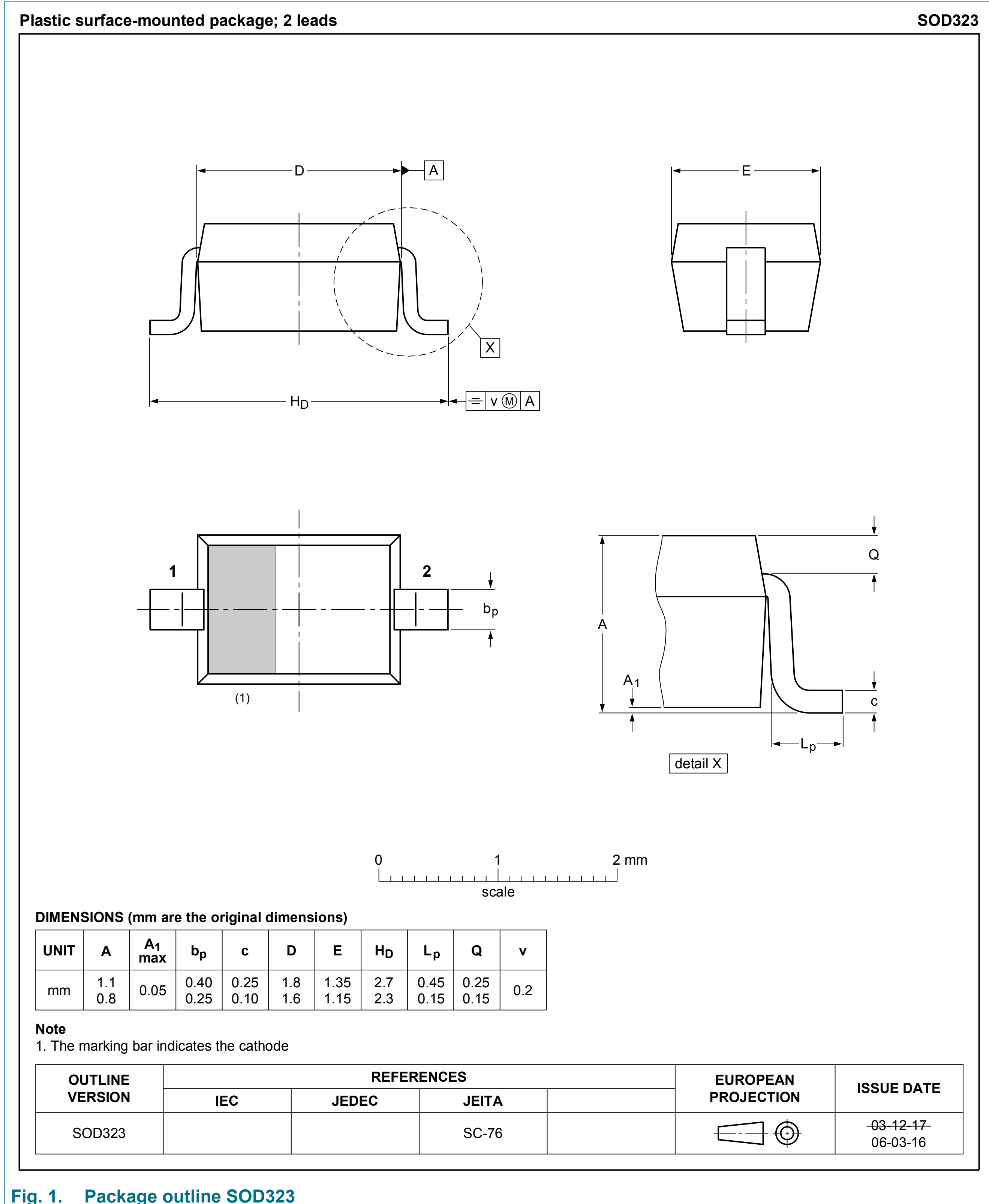
2. Package outline



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	c	D	E	H_D	L_p	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOD323			SC-76			~~03-12-17~~ 06-03-16

Fig. 1. Package outline SOD323

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3. Soldering

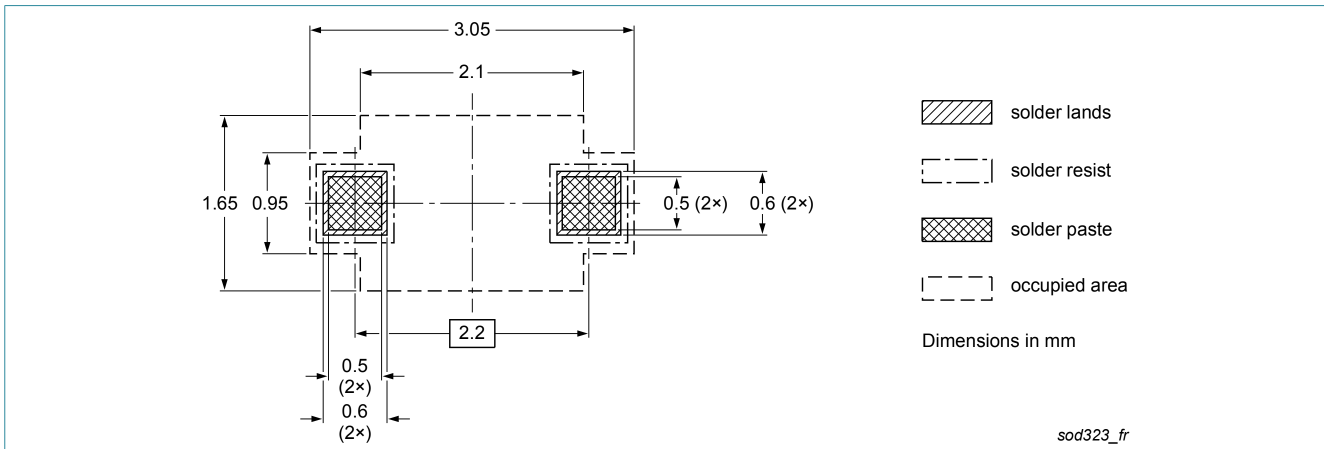

Fig. 2. Reflow soldering footprint for SOD323

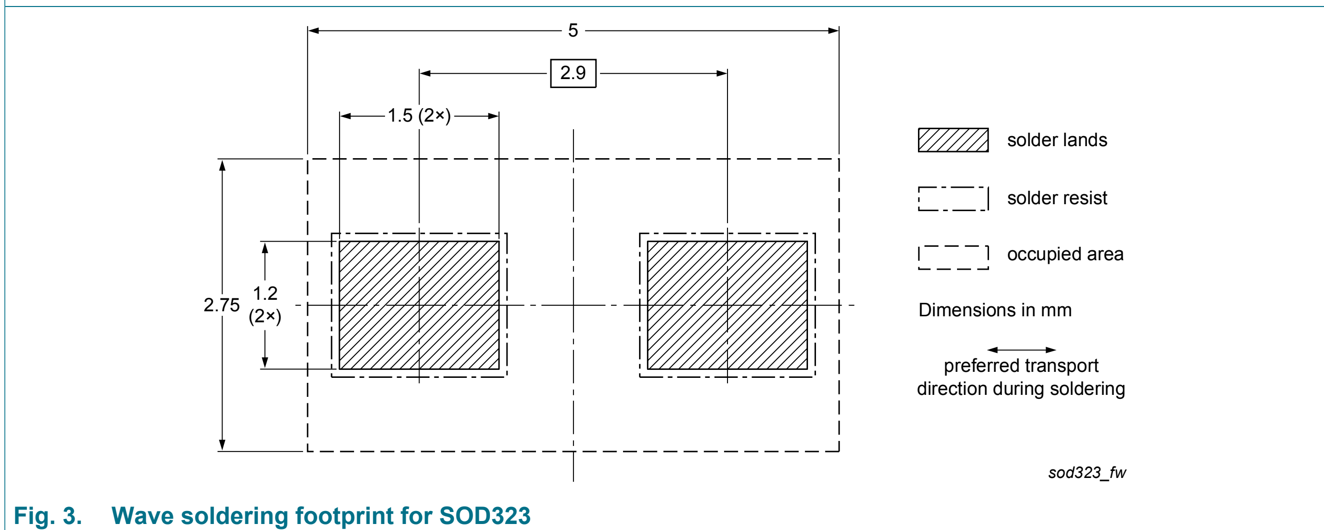

Fig. 3. Wave soldering footprint for SOD323

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